Customer No.: 31561 Application No.: 10/709,179 Docket No.: 10544-US-PA

Examiner: HA, NATHAN W.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Applicants: Chang et al.

Serial No.: 10/709,179

Filed: April 19, 2004

For: STACK-TYPE MULTI-CHIP
PACKAGE AND METHOD OF
FABRICATING BUMPS ON
THE BACKSIDE OF A CHIP

April 19, 2004

AMENDMENT

AMENDMEN

"The Commissioner is authorized to charge the fees indicated in the transmittal letter and any other fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)."

PRELIMINARY AMENDMENT

Mail Stop <u>RCE</u> Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The Office Action dated February 13, 2006, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.